Specification

2.4 Machine Specifications

Productivity

Die Size	UPH
≤ 100 x 100 mil (2.54 x 2.54 mm)	▪ 9.2 K – 10.5K
≥ 100 x 100 mil (2.54 x 2.54 mm) & ≤ 300 x 300 mil (8.89 x 8.89 mm)	▪ 4.2K – 9.2K
≥ 300 x 300 mil (10.16 x 10.16 mm)	▪ 1.4 K – 4.2K

Note: The above UPH quoted are subjected to the following conditions:

- With full inspection disable
- Epoxy stamping is used for die size < 100 mils
- If epoxy writing is used for die size < 100 mils with matrix leadframes, dual writing pin must be used with pad pitch less than 1000 mils

Conversion

Full Conversion	▪ 12 minutes
Device Conversion	▪ 5 minutes
6" – 8" (or vice versa) Conversion	▪ 5 minutes

Workholder Indexer

Transport Method	▪ High speed linear motor gripping mechanism
Resolution	▪ 0.5 µm
Dispense / Bond Position	▪ Individual programmable X, Y & Z axes
Leadframe Orientation Check	▪ Standard
Index Sensor Position	▪ Standard
Leadframe Vacuum Check	▪ Standard

Dispensing System

X Y Travel	▪ 2" (50.8 mm) in X; 3" (76.2 mm) in Y
Resolution	▪ 0.02 mil (0.5 um) in X, Y ▪ 0.15 mil/count (3.81 um/count) in Z

Pick / Bond Head

Pick Force	▪ 30 – 300g
Bond Force	▪ 30 – 2000g
X Y Travel	▪ 4 mm in X; 142 mm in Y

Ejector System

Ejector Upward Movement Travel	▪ 0" – 0.2" (0 - 5 mm) linear programmable

Pattern Recognition System Accuracy

PRS	▪ Multi-grey level PRS (Eagle)
Camera Resolution	▪ 512 x 512 pixel
Grey Scale	▪ 256 grey levels
Positional Accuracy	▪ ±1/4 pixel
Angular Accuracy	▪ ±0.1°
Die Angle Recognition	▪ ±180°